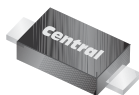


# Material Composition Specification

## SOD-123FL Case



Device average mass ..... 8.34 mg  
 Fluctuation margin ..... +/-10%

Component	Material	Material		Substance	CAS No.	Substance		
		(%wt)	(mg)			(%wt)	(mg)	(ppm)
active device	doped Si	0.47%	0.039	Si	7440-21-3	0.43%	0.036	4,318
				Au	7440-57-5	0.04%	0.003	360
bond wire	gold	0.01%	0.001	Au	7440-57-5	0.01%	0.001	120
leadframe	Cu alloy w/ silver plating	45.6%	3.802	Cu	7440-50-8	44.38%	3.7	443,789
				Fe	7439-89-6	1.08%	0.09	10,795
				Ag	7440-22-4	0.14%	0.012	1,439
encapsulation	EMC	53.12%	4.429	SiO <sub>2</sub>	14808-60-7	38.38%	3.2	383,817
				epoxy resin	29690-82-2	6.6%	0.55	65,969
				phenol resin	9003-35-4	6.6%	0.55	65,969
				Sb <sub>2</sub> O <sub>3</sub>	1309-64-4	0.42%	0.035	4,198
				Br	7726-95-6	1.13%	0.094	11,275
plating	tin alloy	0.8%	0.066	Sn	7440-31-5	0.78%	0.065	7,796
				Bi	7440-69-9	0.02%	0.0013	156

**Disclaimer**

The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R1 (3-June 2011)